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SUBMIT A PAPER FOR SEMI-THERM 42!

As you further develop a technique or application, consider documenting it for the thermal community. **SEMI-THERM 42** will begin accepting abstracts during the summer (deadline is October 1, 2025). We welcome your submissions! Visit us at www.semi-therm.org.

SEMI-THERM 42 is March 2026 – be there!

* -- Extended Abstract only